

15. (New) A method as in claim 9 wherein the surface comprises a low k material.

16. (New) A method as in claim 9 wherein the surface comprises a structure selected from a group consisting of a hard disk and a micro electrical mechanical structure.

17. (New) A method as in claim 9 wherein said directing comprises directing the aqueous solution at a location proximate a carrier of the surface.

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amp.
18. (New) A method as in claim 17 wherein the location is less than one inch downstream of the surface.

19. (New) A method as in claim 9 wherein a pH of the aqueous solution is from about 2 to about 8.

20. (New) A method as in claim 9 wherein the aqueous solution comprises reagents selected from a group consisting of carbonate anions, bicarbonate anions, oxalic acid, formic acid, acetic acid, and glycol acids.

21. (New) A method as in claim 9, further comprising controlling a temperature of the aqueous solution.

22. (New) A method as in claim 21 wherein said controlling comprises lowering the temperature.

23. (New) A method as in claim 21 wherein said controlling comprises refrigerating the aqueous solution.

24. (New) A method as in claim 9, further comprising controlling a concentration of ozone in the aqueous solution.

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WTD 25. (New) A method as in claim 24 wherein said controlling comprises controlling the concentration of ozone such that it is less than or equal to 20 ppm.

26. (New) A method as in claim 9 comprising spin etching of the surface.